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IN - CHOO D H; JUNG S U

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PA - (SMSU) SAMSUNG ELECTRONICS CO LTD

PN - KR2001017690 A 20010305 DW200162 C03B33/02 001pp

PR - KR19990033347 19990813

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XIC - C03B-033/02

AB - KR2001017690 NOVELTY - A process for cutting glass substrate, especially, the corner of glass substrate, by laser-cutting apparatus is provided to minimize the cutting inferiority arising from spreading of crack, which is characterized in that an internal crack is formed along the line to be cut on a glass substrate by the first laser, then cutting is performed by the second laser.

- DETAILED DESCRIPTION - The process comprises the steps of: setting up a line to be cut on a glass substrate, a liquid crystal display panel(300); aligning a focus of the first laser beam comprising at least two laser beam with the line; deriving a crack inside the glass substrate corresponding to the line to be cut by overlapping the first laser from a laser device(210); applying the second laser from a laser device(220) along the line to be cut to heat the glass rapidly; supplying a cooling liquid to the line to cool the glass rapidly.

- (Dwg.1/10)

IW - LASER CUT APPARATUS PROCESS CUT GLASS SUBSTRATE

IKW - LASER CUT APPARATUS PROCESS CUT GLASS SUBSTRATE

INW - CHOO D H; JUNG S U

NC - 001

OPD - 1999-08-13

ORD - 2001-03-05

PAW - (SMSU) SAMSUNG ELECTRONICS CO LTD

TI - Laser-cutting apparatus and process for cutting glass substrate thereby

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SEARCH REPORT